



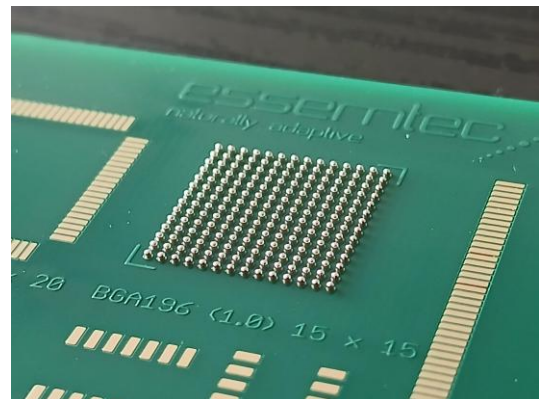
Press Release

SolderKing Ball Attach Flux Validated for Automated BGA Reballing

Essemtec trials demonstrate automated flux jetting with solder spheres down to 300 µm

SolderKing Assembly Materials, a UK manufacturer of soldering products for electronics assembly, has confirmed that its Ball Attach Flux has been successfully tested and validated for use in an automated BGA reballing process. The testing was conducted by Essemtec, an established manufacturer of SMT production systems.

The evaluation demonstrated that SolderKing's Ball Attach Flux could be automatically jetted as part of a process incorporating solder sphere placement and vapour-phase soldering. It provides specific application evidence for the use of the ROLO flux gel in automated ball attach and reballing.



Chris Ward, Chief Operating Officer at SolderKing, said: "Ball attach and reballing work is only getting more demanding, with sphere sizes shrinking and manufacturers under pressure to automate wherever they can. Essemtec's testing shows our Ball Attach Flux handles solder balls down to 300 micron on fully automated equipment. It's a strong result and one that opens up new applications for a product our customers already trust for rework."

Kevin Domancich, Director Technical Sales, Applications and Service at Essemtec, said: "Achieving consistent flux deposition at these small dimensions is critical for automated BGA reballing. Our trials confirmed that SolderKing's Ball Attach Flux can be precisely jetted and successfully integrated into a fully automated process. The results demonstrate the potential of combining high-precision jetting with automated sphere placement to deliver a repeatable and scalable reballing process."

Testing at Essemtec's facility involved jetting a BGA flux pattern onto a printed circuit board, placing the solder spheres and completing the reballing process in a vapour-phase oven.

The work included a 600 µm flux dot for a 500 µm solder ball and a 250 µm flux dot for a 300 µm solder ball. Essemtec reported successful results and confirmed that fully automated dispensing and jetting of the gel was possible.

The trials demonstrated successful processing with solder spheres down to 300 µm. Separately, based on its wider application experience, Essemtec indicated that the process could accommodate solder sphere sizes down to 250 µm. Its team also confirmed that a 250 µm flux dot meets the requirements of most current applications.

SolderKing Ball Attach Flux uses the company's halogen-free flux gel formulation, developed for reworking and repairing components assembled using leaded and lead-free solder alloys. The successful trials demonstrate its suitability for automated ball attach and BGA reballing processes.

The clear, tacky material is a halogen-free, no-clean flux classified ROL0 in accordance with J-STD-004A. It provides wetting across different board finishes and produces residues that can be removed when required. The gel is RoHS and REACH compliant and is available in syringe and tub packaging.

SolderKing manufactures its products at its facility in Bridlington, Yorkshire. Its range includes solder alloys, cored solder wires, solder pastes, repair gels and fluxes for electronics assembly.

www.SolderKing.com

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Editor's Notes:

SolderKing Assembly Materials Ltd:

SolderKing Assembly Materials Limited is an independent UK manufacturer of solders and chemical consumables for the assembly of electronic, electrical, and engineered parts. Established in 2018, SolderKing specialises in developing, manufacturing, and distributing regulatory-compliant soldering assembly materials and provides a comprehensive range of technical support services to help its customers achieve optimal performance.

For more information visit www.SolderKing.com

Essemtec:

Essemtec is a leader in flexible solutions for Surface Mount Technology (SMT), offering advanced Pick-and-Place systems as well as specialized high-speed solder paste dispensing and jetting platforms. With a strong focus on integrated All-in-One production concepts, Essemtec supports high-mix, low-to-medium volume manufacturing, Advanced Packaging applications, and the most demanding dispensing processes. Its portfolio ranges from dedicated dispensing and jetting systems to versatile All-in-One platforms that combine placement, dispensing, and inspection, complemented by intelligent material management solutions and the Lizard reflow oven.

Our Focus – Your Solution.

For more information visit: www.essemtec.com/en/